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(54) Title: CHEMICAL MECHANICAL POLISHING SLURRY COMPOSITION FOR POLISHING POLYCRYSTALLINE SILICON FILM AND METHOD FOR PREPARING THE SAME

(57) Abstract: Disclosed herein are a chemical mechanical polishing (CMP) slurry for polishing a polycrystalline silicon film and a method for producing the slurry. The CMP slurry comprises a blend of metal oxide abrasive particles in ultrapurewater and additives, including a non-ionic fluorine type surfactant and a quaternary ammonium base. The CMP slurry can provide a CMP slurry composition that has superior within-wafer-non-uniformity and improved selectivity and solves the problem of dishing.

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